



# CIRTEK ELECTRONICS CORPORATION

116 East Avenue, Phase V, SEZ Laguna Technopark  
Biliran, Laguna, Philippines

## PRODUCT INFORMATION

Customer :

Device :

Device ID :

Die Size :

Wafer Material :

Package Type:

14L SOIC NB

No. of Wires :

## MATERIAL INFORMATION

Leadframe :

A194 with spot Ag

Pad Size : 90 X 110 mils

Epoxy :

Gold Wire :

Molding Compound :

Lead Finish :

## MARKING INSTRUCTION

TOP :

BOTTOM :

BONDING DIAGRAM NO.

REF. BONDING DIAGRAM NO.

SCALE

not to scale

DRAWN BY:

REVIEWED BY :

### REVISION NO.

### APPROVALS

REV. #

DESCRIPTION

ECN #

DEPT

APPROVALS

DATE

CUST

QSM

QC

MFG

Note:

